



## Material Content Data Sheet



<b>Sales Product Name</b>		IPS80R1K4P7		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA002116540						
<b>Package</b>		PG-TO251-3-344		<b>Weight*</b>		334.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.500	0.45	0.45	4486	4486
leadframe	inorganic material	phosphorus	7723-14-0	0.046	0.01		139	
	non noble metal	iron	7439-89-6	0.154	0.05		462	
	non noble metal	copper	7440-50-8	154.154	46.13	46.19	461201	461802
	non noble metal	aluminium	7429-90-5	0.391	0.12	0.12	1170	1170
wire	non noble metal	aluminium	7429-90-5	0.391	0.12	0.12	1170	1170
encapsulation	organic material	carbon black	1333-86-4	0.446	0.13		1333	
	plastics	epoxy resin	-	13.517	4.04		40442	
	inorganic material	silicondioxide	60676-86-0	134.581	40.26	44.43	402641	444416
leadfinish	non noble metal	tin	7440-31-5	4.142	1.24	1.24	12392	12392
plating	non noble metal	nickel	7440-02-0	0.607	0.18	0.18	1815	1815
solder	non noble metal	tin	7440-31-5	0.036	0.01		108	
	noble metal	silver	7440-22-4	0.045	0.01		135	
	non noble metal	lead	7439-92-1	1.729	0.52	0.54	5173	5416
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		21	
	non noble metal	iron	7439-89-6	0.023	0.01		68	
	non noble metal	copper	7440-50-8	22.867	6.84	6.85	68414	68503
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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